

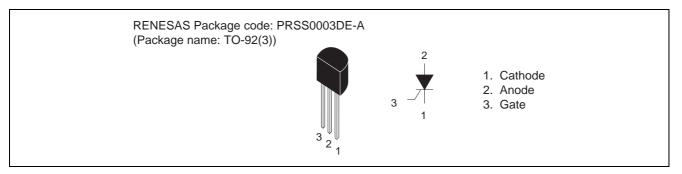
Thyristor Low Power Use

REJ03G0542-0100 Rev.1.00 Mar.28.2005

Features

- $I_{T(AV)}: 0.3 A$
- V_{DRM} : 400 V
- I_{GT} : 100 μA

Outline



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Planar Passivation Type

Completed Pb free product

Applications

Solid state relay, leakage protector, fire alarm, timer, ring counter, electric blanket, protective circuit for acoustic equipment, strobe flasher, and other general purpose control applications

Maximum Ratings

Parameter	Symbol	Voltage class	Unit	
Falameter	Symbol	8		
Repetitive peak reverse voltage	V _{RRM}	400	V	
Non-repetitive peak reverse voltage	V _{RSM}	500	V	
DC reverse voltage	V _{R (DC)}	320	V	
Repetitive peak off-state voltage ^{Note1}	V _{DRM}	400	V	
DC off-state voltage ^{Note1}	V _{D (DC)}	320	V	

Parameter	Symbol	Ratings	Unit	Conditions
RMS on-state current	I _{T (RMS)}	0.47	А	
Average on-state current	I _{T (AV)}	0.3	A	Commercial frequency, sine half wave 180° conduction, Ta = 30°C
Surge on-state current	I _{TSM}	10	A	60Hz sine half wave 1 full cycle, peak value, non-repetitive
l ² t for fusing	l ² t	0.4	A ² s	Value corresponding to 1 cycle of half wave 60Hz, surge on-state current
Peak gate power dissipation	P _{GM}	0.1	W	
Average gate power dissipation	P _{G (AV)}	0.01	W	
Peak gate forward voltage	V _{FGM}	6	V	
Peak gate reverse voltage	V _{RGM}	6	V	
Peak gate forward current	I _{FGM}	0.1	A	
Junction temperature	Tj	- 40 to +125	°C	
Storage temperature	Tstg	- 40 to +125	°C	
Mass	—	0.23	g	Typical value

Notes: 1. With gate to cathode resistance $R_{GK} = 1 \ k\Omega$.

Electrical Characteristics

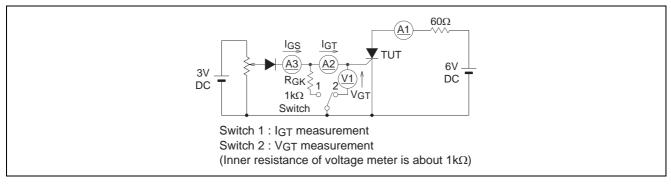
Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions
Repetitive peak reverse current	I _{RRM}	—	—	0.1	mA	Tj = 125°C, V _{RRM} applied
Repetitive peak off-state current	I _{DRM}	—	—	0.1	mA	Tj = 125°C, V _{DRM} applied,
						$R_{GK} = 1 \ k\Omega$
On-state voltage	V _{TM}	—	—	1.6	V	Ta = 25°C, I _{TM} = 0.6 A,
						instantaneous value
Gate trigger voltage	V _{GT}	—	—	0.8	V	$Tj = 25^{\circ}C, V_{D} = 6 V,$
						$I_T = 0.1 A^{Note3}$
Gate non-trigger voltage	V_{GD}	0.2	—	—	V	$Tj = 125^{\circ}C, V_D = 1/2 V_{DRM},$
						$R_{GK} = 1 \ k\Omega$
Gate trigger current	I _{GT}	20	_	100 ^{Note2}	μΑ	$Tj = 25^{\circ}C, V_{D} = 6 V,$
						$I_T = 0.1 A^{Note3}$
Holding current	Ι _Η	_	_	3	mA	$Tj = 25^{\circ}C, V_{D} = 12 V,$
						$R_{GK} = 1 \ k\Omega$
Thermal resistance	R _{th (j-a)}	_	_	180	°C/W	Junction to ambient

Notes: 2. If special values of I_{GT} are required, choose item E from those listed in the table below if possible.

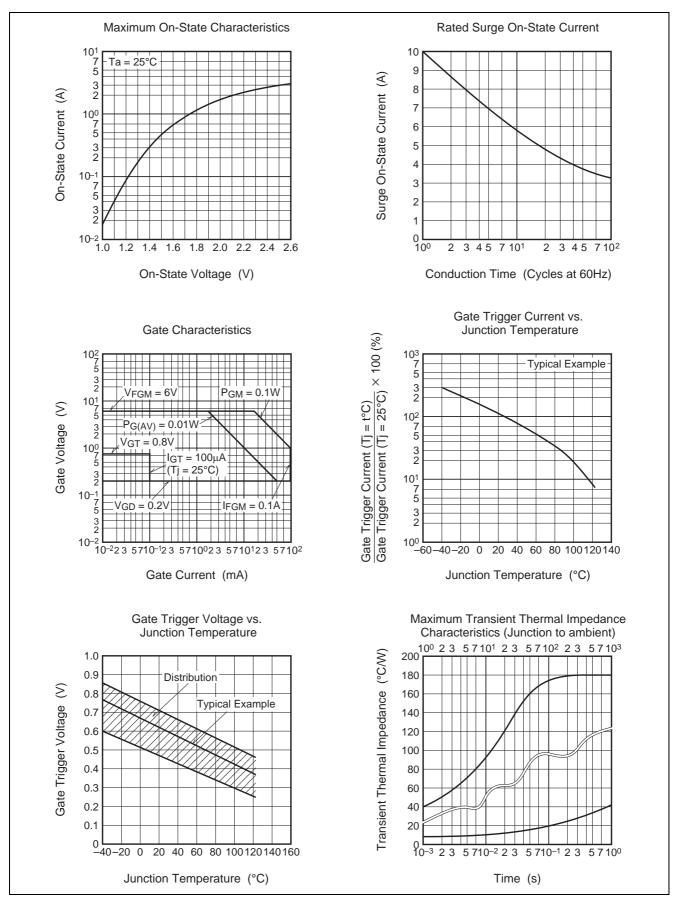
ltem	В	E	
I _{GT} (μΑ)	20 to 50	20 to 100	

The above values do not include the current flowing through the 1 $k\Omega$ resistance between the gate and cathode.

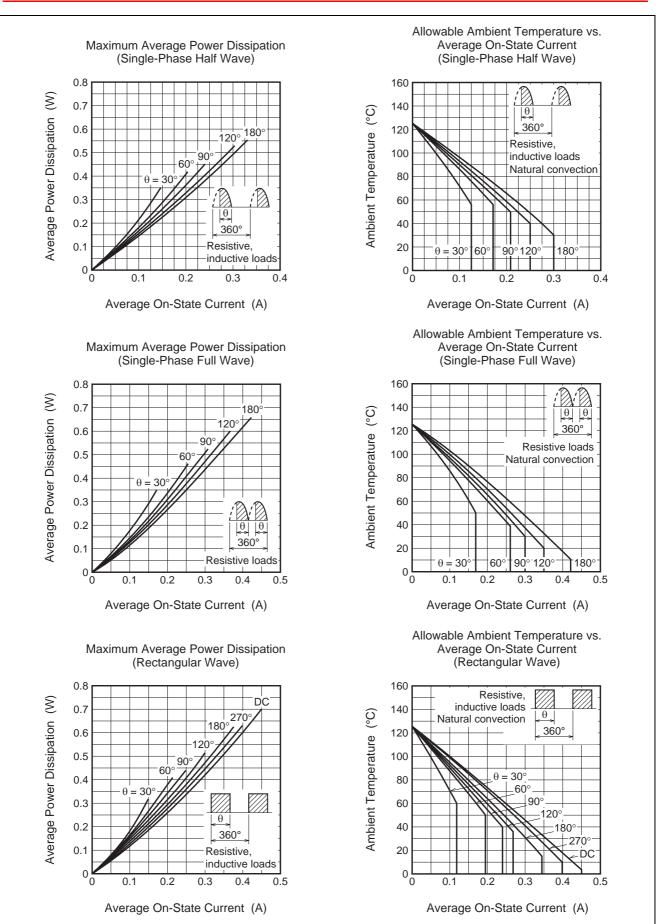
3. I_{GT} , V_{GT} measurement circuit.



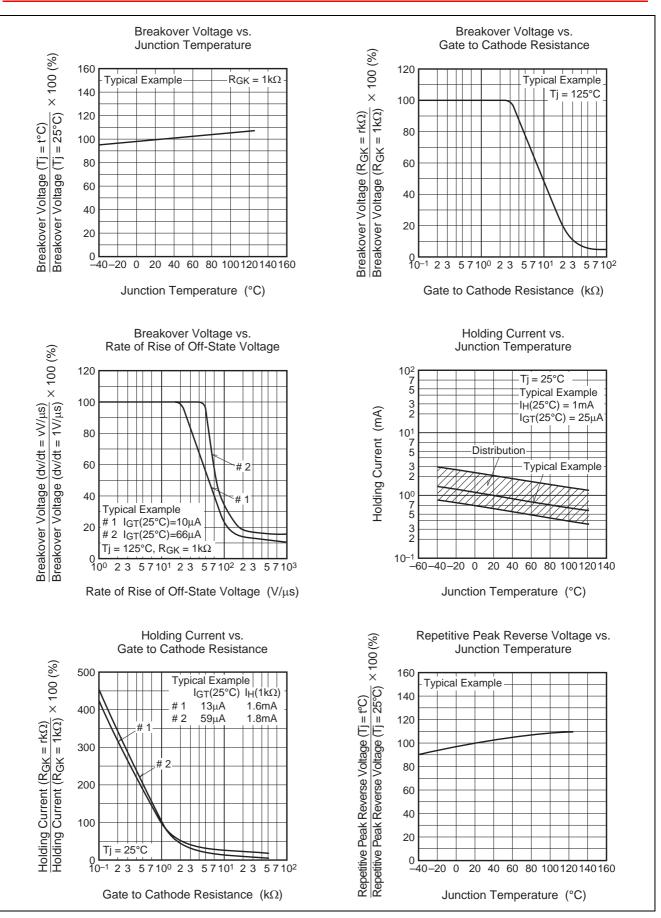
Performance Curves



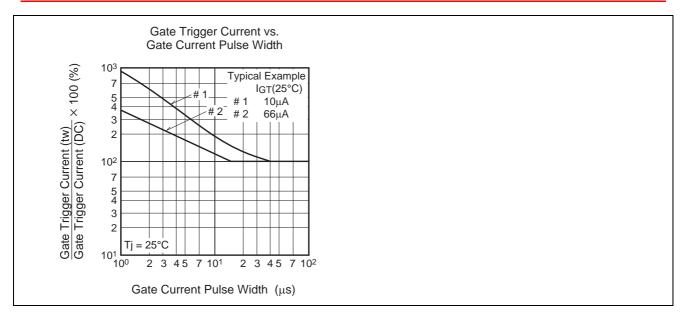




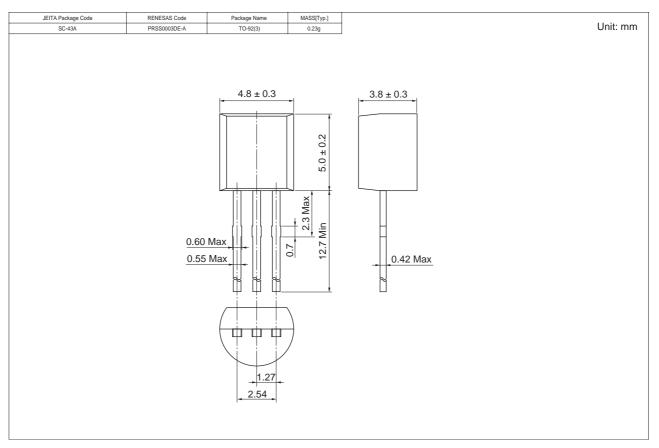




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Package Dimensions



Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Vinyl sack	500	Type name	CR02AM-8-E
Form A8	Taping	2500	Type name – ETZ	CR02AM-8-ETZ

Note : Please confirm the specification about the shipping in detail.

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